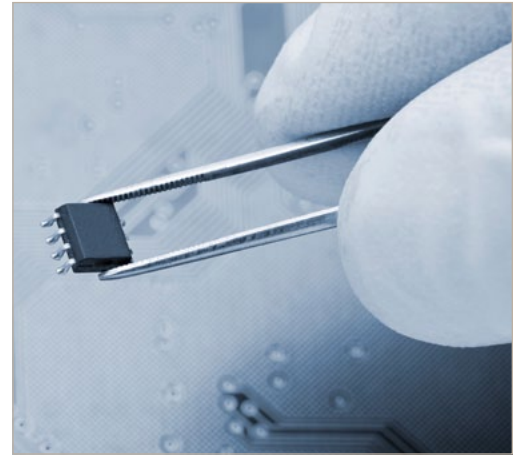


# FF302-75

ULTRA FFKM for Semiconductor  
High End Deposition Applications



## Extremely Low Etch & Metals:

Parker has developed FF302, a uniquely formulated perfluoroelastomer that provides the ideal solution for high end deposition applications where wafer yield is critical. Historically, non-filled technologies have offered very low metals content but erode rapidly in aggressive chemistries requiring frequent seal change. Metal oxide filled technologies offered improved etch resistance but higher risk of contamination due to that same metallic content. Parker Ultra™ FF302 answers that conundrum by offering excellent etch resistance in oxygen and fluorine plasmas while maintaining extremely low metals.



## Contact Information:

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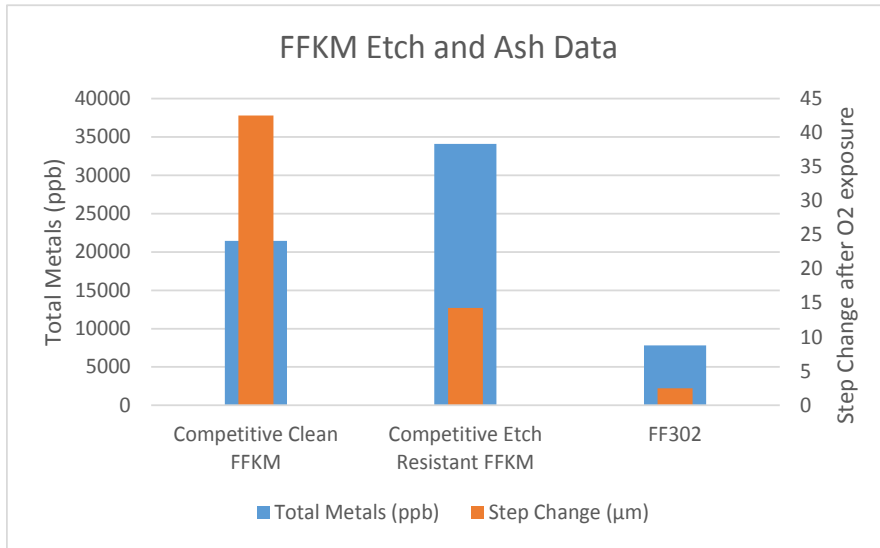
## Features:

- Maximum operating temperature 600°F (315° C)
- Lowest extractables
- Extremely low metallic ion content
- Low particle generation
- Excellent oxygen and fluorine plasma resistance



ENGINEERING YOUR SUCCESS.

## FF302-75 Material Data



### Extremely Resistant:

FF302 provides robust sealing against CF<sub>4</sub>, NF<sub>3</sub>, O<sub>2</sub> and O<sub>3</sub> plasmas making it an excellent option for not only deposition but for etch processes as well. FF302 exhibits a much slower etch rate even compared to products that are developed for specifically etch resistance.

### Purity:

In semiconductor processing it is critical that any generation of foreign material is mitigated. Seals have traditionally been a likely avenue for particles to be generated in the harsh environments of wafer processing. FF302 was developed to be cleaner than traditional, clean technologies.

| Property   | Typical Results |
|--|-----------------|
| <b>Original Properties, ASTM D2240, D1414</b>        |                 |
| Shore A Hardness                                     | 75              |
| Tensile Strength, psi                                | 1198            |
| Modulus at 100% Elongation                           | 562             |
| Ultimate Elongation, %                               | 210             |
| <b>Compression Set, ASTM D395 Method B</b>           |                 |
| 70 hours @ 446° F( 230° C), % of original deflection | 19              |

